

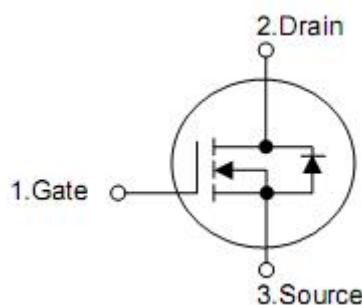
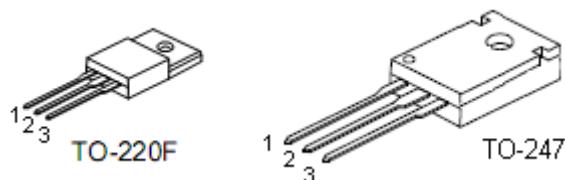
1. Description

The KIA18N50H N-Channel enhancement mode silicon gate power MOSFET is designed for high voltage, high speed power switching applications such as high efficiency switched mode power supplies, active power factor correction.

2. Features

- $R_{DS(on)}=0.25\Omega$ @ $V_{GS}=10V$
- Low gate charge (typical 50nC)
- Fast switching capability
- Avalanche energy specified
- Improved dv/dt capability

3. Pin configuration



Pin	Function
1	Gate
2	Drain
3	Source

4. Absolute maximum ratings

(T _c = 25 °C , unless otherwise notes)					
Parameter	Symbol	Ratings		Units	
		TO220F	TO247		
Drain-source voltage	V _{DSS}	500		V	
Gate-source voltage	V _{GSS}	+30		V	
Drain current continuous	T _c =25°C	I _D	18.0*	18.0	A
	T _c =100°C		10.8*	10.8	A
Drain current pulsed (note1)	I _{DP}	72*	72		A
Avalanche energy	Repetitive (note1)	E _{AR}	23.5	23.5	mJ
	Single pulse (note2)	E _{AS}	990	990	mJ
Peak diode recovery dv/dt (note 3)	dv/dt		4.5		V/ns
Total power dissipation	T _c =25°C	P _D	38.5	235	W
	derate above 25°C		0.3	1.88	W/°C
Junction temperature	T _J		+150		°C
Storage temperature	T _{STG}		-55~+150		°C

*Drain current limited by maximum junction temperature.

5. Thermal characteristics

Parameter	Symbol	Ratings		Units
		TO220F	TO247	
Thermal resistance,junction-ambient	R _{thJA}	62.5	40	°C/W
Thermal resistance,case-to-sink typ.	R _{thCS}	-	-	
Thermal resistance,Junction-case	R _{thJC}	3.3	0.52	

6. Electrical characteristics

($T_J=25^\circ\text{C}$, unless otherwise notes)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Off characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	500	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=500\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
		$V_{\text{DS}}=400\text{V}, T_{\text{C}}=125^\circ\text{C}$	-	-	10	μA
		$V_{\text{GS}}=30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	100	nA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}}=-30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	-100	nA
		$V_{\text{GS}}=30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	100	nA
Breakdown voltage temperature coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$I_{\text{D}}=250\mu\text{A}$	TO220F	-	0.6	
			TO247	-	0.5	$\text{V}/^\circ\text{C}$
On characteristics						
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	3.0	-	5.0	V
Static drain-source on-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=9\text{A}$	-	0.25	0.32	Ω
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	2500	-	pF
Output capacitance	C_{oss}		-	400	-	pF
Reverse transfer capacitance	C_{rss}		-	40	-	pF
Switching characteristics						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=250\text{V}, I_{\text{D}}=18.0\text{A}, R_{\text{G}}=25\Omega$ (note4,5)	-	70	-	ns
Rise time	t_r		-	190	-	ns
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	100	-	ns
Fall time	t_f		-	100	-	ns
Total gate charge	Q_g	$V_{\text{DS}}=400\text{V}, I_{\text{D}}=18.0\text{A}, V_{\text{GS}}=10\text{V}$ (note4,5)	-	50	-	nC
Gate-source charge	Q_{gs}		-	14	-	nC
Gate-drain charge	Q_{gd}		-	22	-	nC
Drain-source diode characteristics						
Drain-source diode forward voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{SD}}=18.0\text{A}$	TO220F	-	-	1.5
			TO247	-	-	1.4
Continuous drain-source current	I_{SD}			-	-	18.0
Pulsed drain-source current	I_{SM}			-	-	72
Reverse recovery time	t_{rr}	$I_{\text{SD}}=18.0\text{A}$ $dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$ (note4)	-	550	-	ns
Reverse recovery charge	Q_{rr}		-	5.5	-	μC

Note:1 Repetitive rating: pulse width limited by maximum junction temperature

2. $L=5.5\text{mH}, I_{\text{AS}}=18.0\text{A}, V_{\text{DD}}=50\text{V}, R_{\text{G}}=25\Omega$, staring $T_J=25^\circ\text{C}$

3. $I_{\text{SD}} \leq 18.0\text{A}, dI/dt \leq 200\text{A}/\mu\text{s}, V_{\text{DD}} \leq \text{BV}_{\text{DSS}}$, staring $T_J=25^\circ\text{C}$

4. Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

5. Essentially independent of operating temperature

7. Test circuits and waveforms

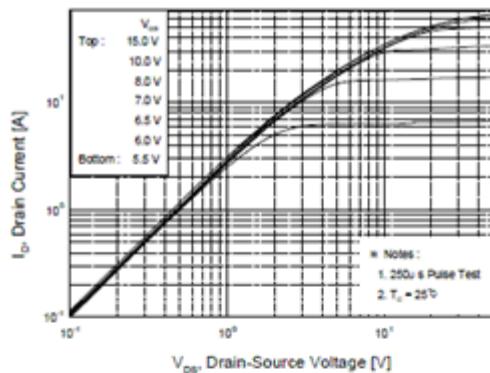


Figure 1. On-Region Characteristics

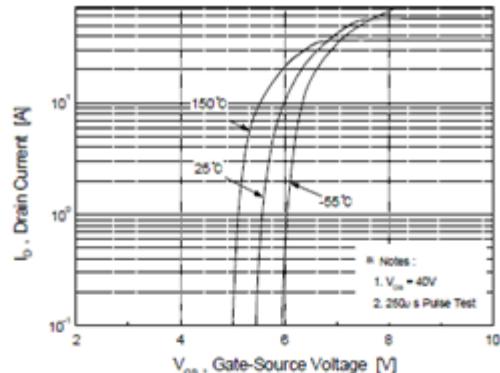


Figure 2. Transfer Characteristics

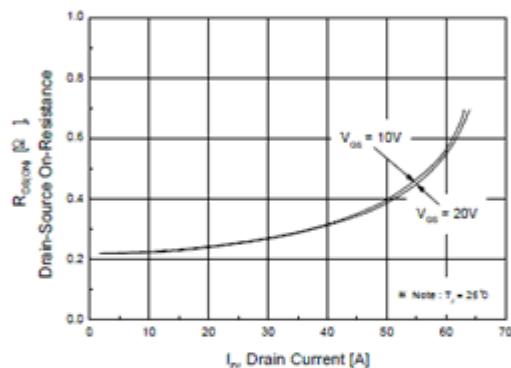


Figure 3. On-Resistance Variation vs
Drain Current and Gate Voltage

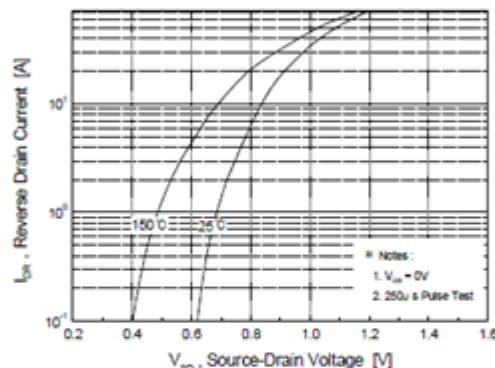


Figure 4. Body Diode Forward Voltage Variation
with Source Current and Temperature

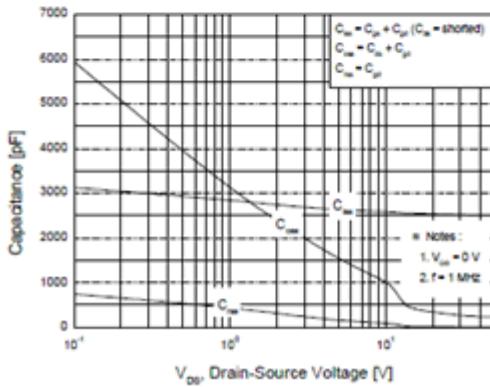


Figure 5. Capacitance Characteristics

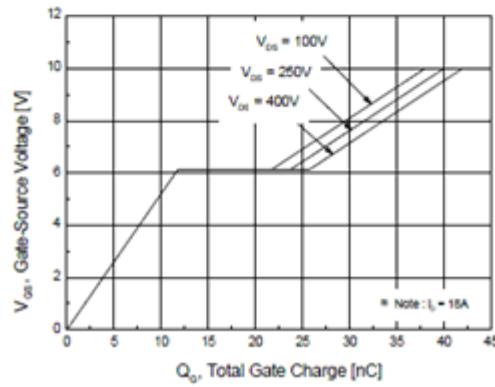


Figure 6. Gate Charge Characteristics

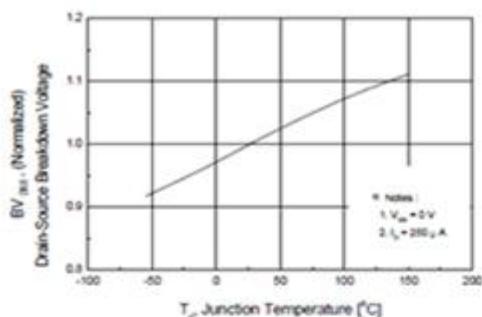


Figure 7. Breakdown Voltage Variation vs Temperature

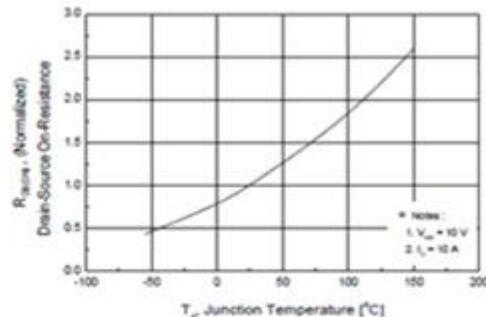


Figure 8. On-Resistance Variation vs Temperature

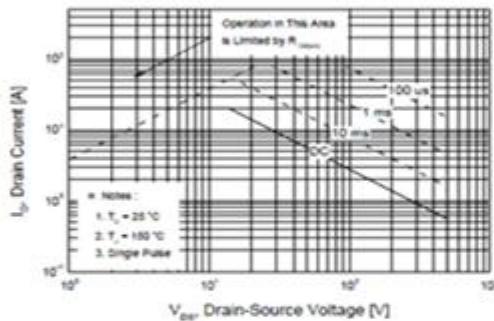


Figure 9. Maximum Safe Operating Area

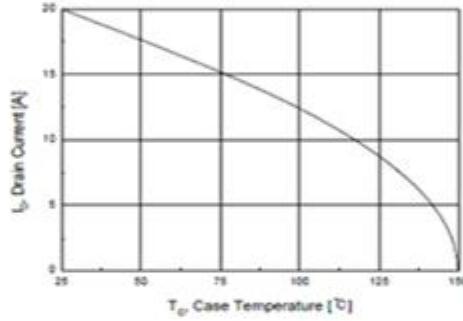


Figure 10. Maximum Drain Current vs Case Temperature

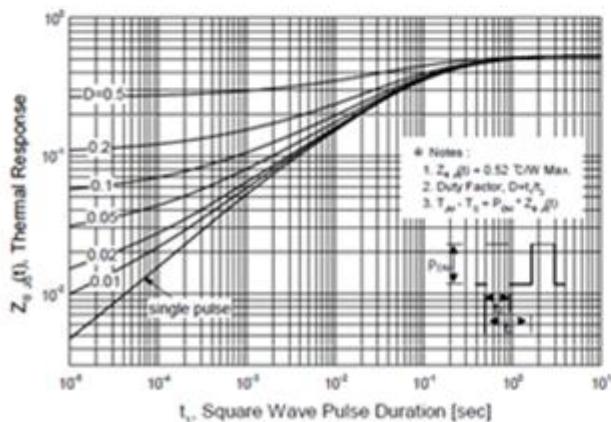


Figure 11. Transient Thermal Response Curve for To-247

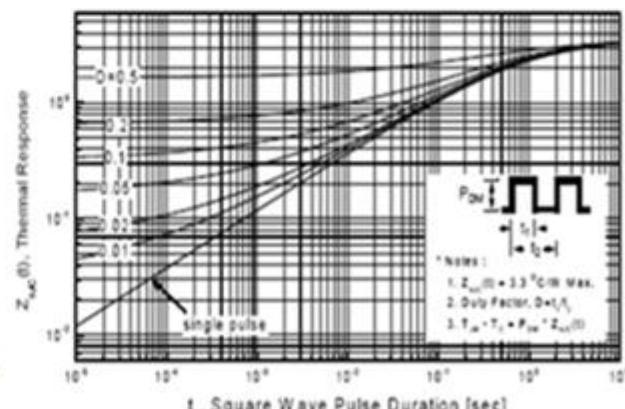


Figure 11-1. Transient Thermal Response Curve for To-220F